

W86L388D Data Sheet



W86L388D
Winbond Host Interface
SD/MMC Memory Card
Bridge

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1. GENERAL DESCRIPTION

The W86L388D is a SD/MMC host interface bridge used between host microprocessor and SD/MMC. The data width of host microprocessor can be 8-bit or 16-bit. W86L388D can support synchronous or asynchronous type of host interface. It also supports DMA or Interrupt type of transfer mode to improve data transfer performance between host microprocessor and SD/MMC. W86L388D is fit for most of IA devices, such as PDA, Cellular Phone, DSC, and MP3 player.

2. FEATURES

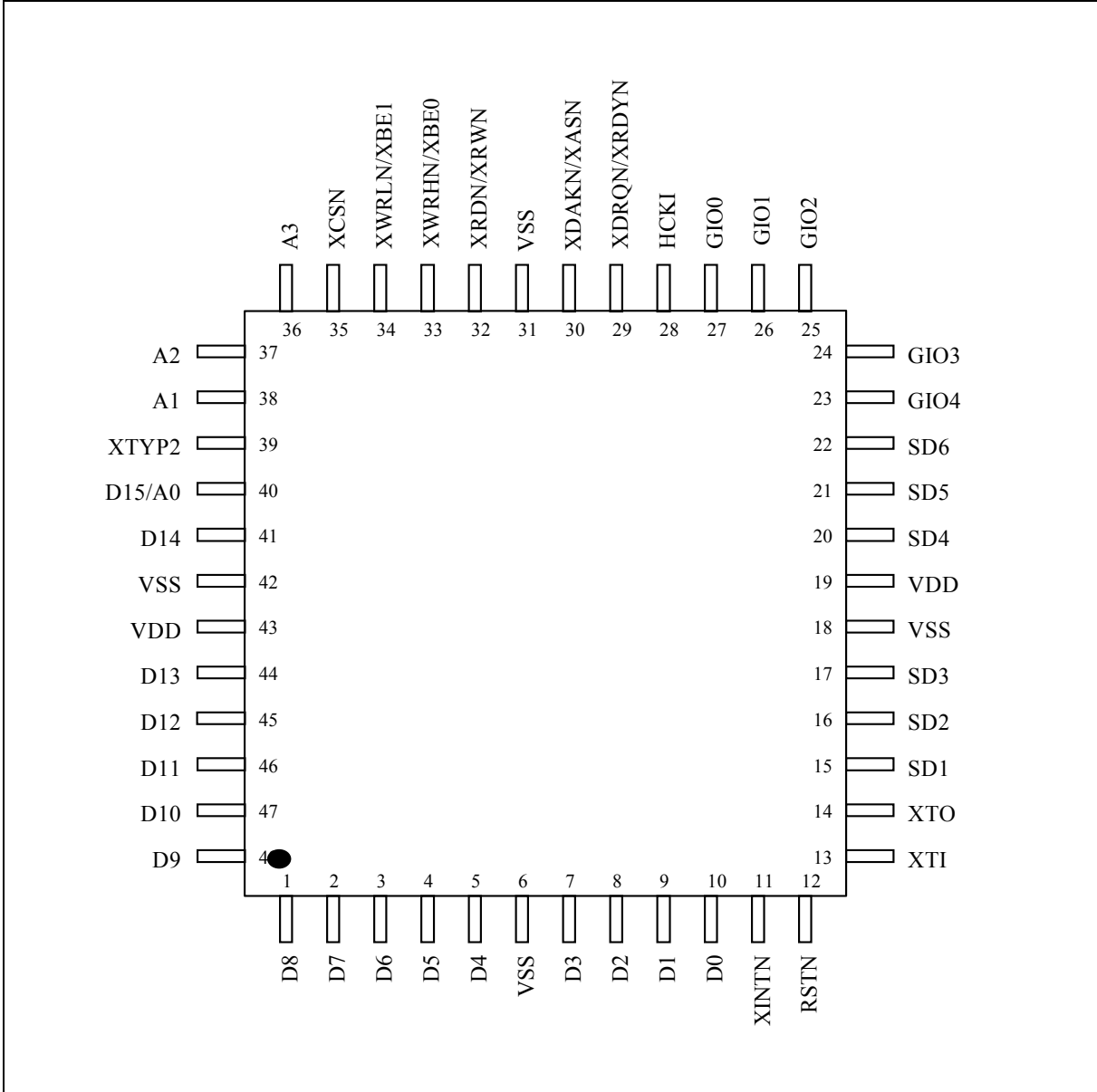
- Compliant with SD spec. Version 1.0
- Compliant with MMC spec. Version 2.2
- Support two types of host microprocessor interface access--synchronous and asynchronous mode
- DMA and Interrupt transfer mode supported
- Host microprocessor 8/16 bit data bus
- Built-in crystal driver circuit, support external oscillator or crystal clock
- Extra 5 programmable GPIO supported
- Wide range of clock input from 3.58MHz up to 25MHz
- 3.3V operation
- 48-pin LQFP package

Ordering Information

Part Number	Package Type	Production Flow
W86L388D	48-PIN LQFP	Commercial, 0°C to +70°C



3. PIN CONFIGURATION





4. PIN DESCRIPTIONS

PIN	NAME	TYPE	DESCRIPTION
SD Interface:			
21	SD5	DO/DI	SD connection #5
22	SD6	DO/DI	SD connection #6
15	SD1	DO/DI	SD connection #1
16	SD2	DO/DI	SD connection #2
17	SD3	DO	SD connection #3
20	SD4	DO	SD connection #4
Crystal Driver:			
13	XTI	DI	Clock driver input signal, may be used as external clock input.
14	XTO	DO	Clock driver output signal.
Host Interface Signal:			
28	HCKI	DI	Host clock input.
35	XCSN	DI	Chip select input pin, active low.
36:38	A[3:1]	DI	Address input pins.
40	D15/A0	DI/DO	Data bus D15 pin, D[15:8] is the high byte of the data bus, D15 also used as A0 when 8-bit CPU data size. In 8-bit mode, internal register high byte (D15:8) will accessed at data bus [7:0] when A0 = 1, low byte (D7:0) will accessed at data bus [7:0] when A0 = 0.
41	D14	DI/DO	Data bus D14 pin.
44:48	D[13:9]	DI/DO	Data bus [13:9] pins.
1:5	D[8:4]	DI/DO	Data bus [8:4] pins, D[7:0] is the low byte of the data bus.
7:10	D[3:0]	DI/DO	Data bus [3:0] pins.
33	XWRHN/ XBE0	DI	Type 1: High byte (D15 to D8) write control pin, active low. Type 2: High byte (D15 to D8) data valid pin, active low.
34	XWRLN/ XBE1	DI	Type 1: Low byte (D7 to D0) write control pin, active low. Type 2: Low byte (D7 to D0) data valid pin, active low.



4. PIN Descriptions, continued

PIN	NAME	TYPE	DESCRIPTION
32	XRDN/ XRWN	DI	Type 1: Read control pin, active low. Type 2: Read write control pin, 1: read 0: write
11	XINTN	DO	Interrupt request pin, active low.
30	XDAKN/ XASN	DI	Type 1: DMA transfer acknowledge pin, active low. Type 2: Bus access cycle start pin, active low.
29	XDRQN/ XRDYN	DO	Type 1: DMA transfer request pin, active low. Type 2: Bus cycle complete pin, active low.
39	XTYP2	DI	Host interface type 2 select pin, 0 : type 1 mode. 1 : type 2 mode.
General I/O Port Signal (SD I/F):			
27:23	GIO[0:4]	DI/DO	5-bit general input output port signals. GIO0 pin can be used as dedicate card detection.
Other Signal:			
12	RSTN	DI	Reset input, hardware reset input, active low.
Power:			
19,43	VDD	DP	Power supply 3.3V
6,18, 31,42	VSS	DP	Ground

Type: DP is Power, DI is Digital Input, DO is Digital Output.



4.1 BLOCK DIAGRAM

4.1.1 Block Diagram

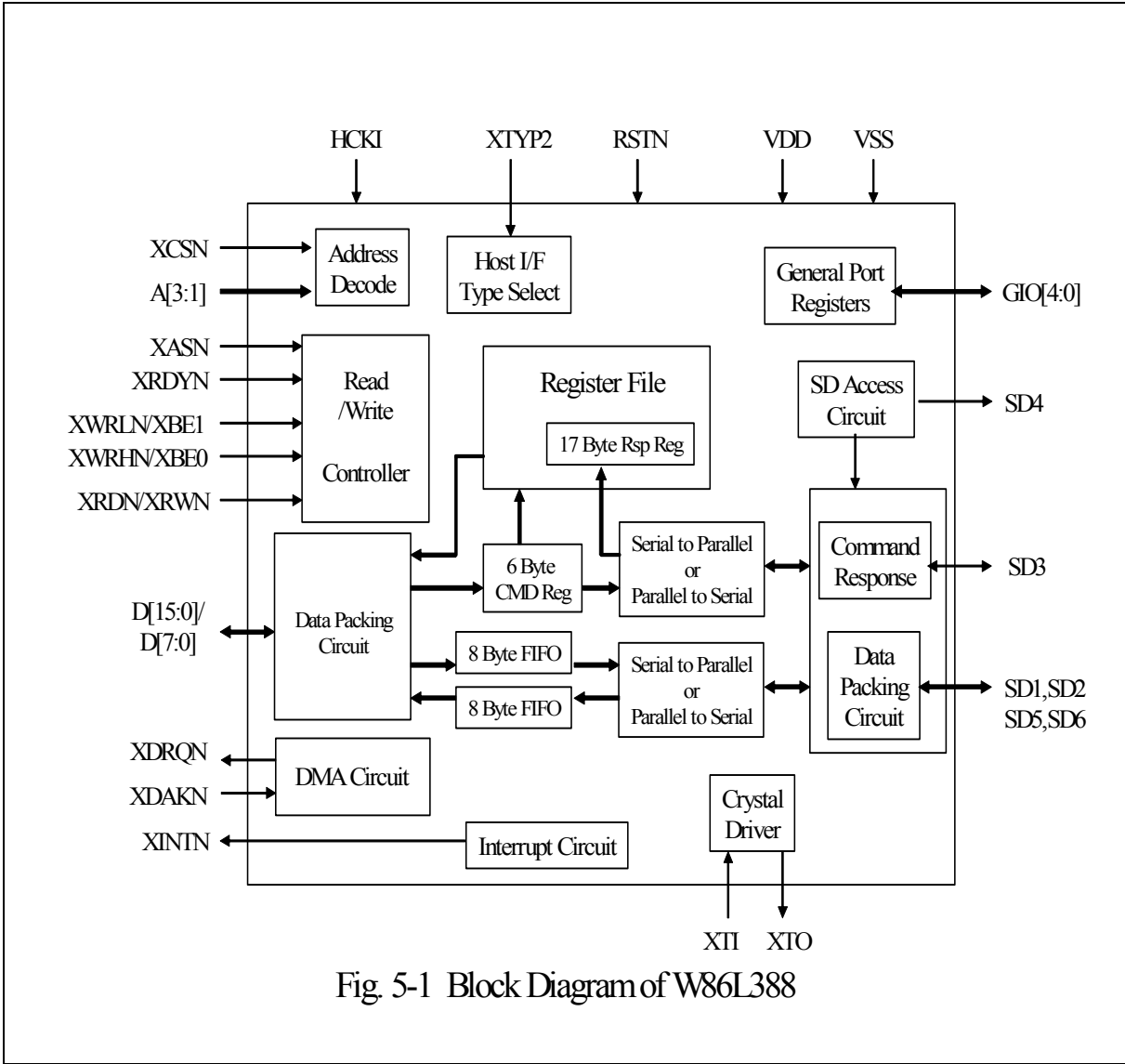


Fig. 5-1 Block Diagram of W86L388



5. REGISTER

The registers in the W86L388 are direct access registers and indirect access registers. The direct access registers and indirect access registers are listed as follows:

Addr	Register Name	Content (note 2)															
		A[3:1]	(note 1)	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2
Direct Access Registers:																	
000	Command Pipe Reg. (WO)	Command pipe registers / Response registers															
	Response Reg. (RO)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
001	Status Reg. (RO)	Status								-	-	-	-	-	-	-	-
		0	0	0	0	1	0	0	0	-	-	-	-	-	-	-	-
001	Control Reg. (RW)	Control								-	-	-	-	-	-	-	-
		0	0	0	0	0	0	0	1	0	-	-	-	-	-	-	-
010	Receive Data Buffer (R/O)	Receive data buffer															
		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
010	Transmit Data Buffer (WO)	Transmit data buffer															
		X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X
011	Interrupt Status Reg. (RC)	Interrupt status								-	-	-	-	-	-	-	-
		0	0	0	0	0	0	0	0	-	-	-	-	-	-	-	-
011	Interrupt Enable Reg. (RW)	Interrupt enable								0	0	0	0	0	1	1	0
		-	-	-	-	-	-	-	-	0	0	0	0	0	1	1	0
100	General I/O Port Data Reg. (RW)	GIO data								-	-	-	-	-	-	-	-
		0	0	0	X	X	X	X	X	-	-	-	-	-	-	-	-
100	General I/O Port Control Reg. (RW)	GIO control								0	0	0	0	0	0	0	0
		-	-	-	-	-	-	-	-	0	0	0	0	0	0	0	0
101	General IP Interrupt Status Reg. (RC)	GIO interrupt status								-	-	-	-	-	-	-	-
		0	0	0	0	0	0	0	0	-	-	-	-	-	-	-	-
101	General IP Interrupt Enable Reg. (RW)	GIO interrupt enable								0	0	0	0	0	0	0	0
		-	-	-	-	-	-	-	-	0	0	0	0	0	0	0	0
110	Index Address Reg. (RW)	Index address															
		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
111	Index Data Register	Index data register															
		X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X



REGISTER, continued

Addr	Register Name	Content (note 2)															
A[3:1]	(note 1)	B15	B14	B13	B12	B11	B10	B9	B8	B7	B6	B5	B4	B3	B2	B1	B0
Indirect Access Registers:																	
000	Extend Status Reg. (RO)	Extend status								-	-	-	-	-	-	-	-
		0	0	0	0	0	0	0	0								
000	Setting Reg. (R/W)	-	-	-	-	-	-	-	-	Setting register							
										0	0	1	0	0	0	0	1
001	Data Format Register (R/W)	W	-	-	-	Data length											
		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
010	Nac Time-out Register (R/W)	Nac time out register															
		0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
011	Error Status Reg. (RO)	Status								-	-	-	-	-	-	-	-
		0	0	0	0	0	0	0	0								
100	Ready & Data Size Register (R/W)	F	-	-	-	-	-	-	8-	Test							
		0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

Note 1: R/W means the register can be read and write.

RO means the register is read only.

RC means the register is read only and read clear.

WO means the register is write only.

Note 2: The data bit in the content is the initial value during hardware reset.

0: the bit value is 0.

1: the bit value is 1.

X: the bit value is unknown.

-: Undefined bit in the register and the value will read 0.



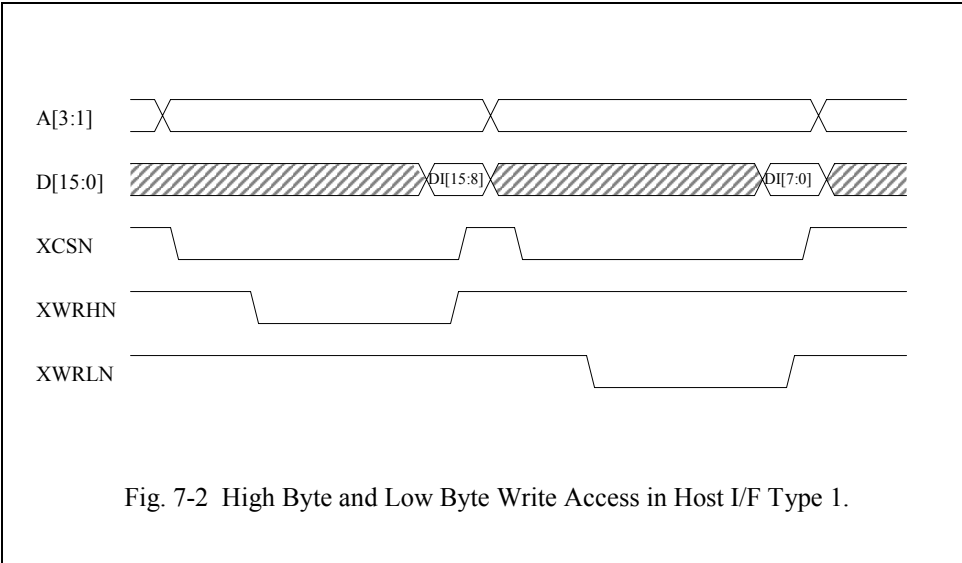
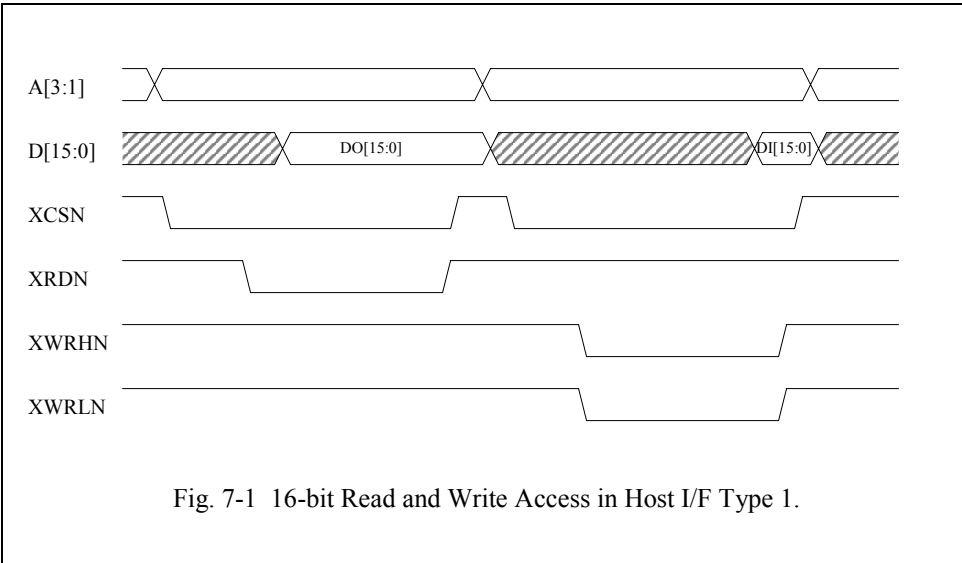
6. FUCNTIONAL DESCRIPTION

6.1 Host Interface

The Host interface type may be type 1 or type. The read cycle always 16-bit access and the write cycle may be 16-bit access or high byte or low byte access.

Host Interface Type 1:

The Host interface type 1 is selected when XTYP2 pin is low. Figure 7-1 shows the timing of CPU read and write in type 1. Figure 7-2 is the timing of CPU write high byte and write low byte.





Host Interface Type 2:

The Host interface type 2 is selected when XTYP2 pin is high. Figure 7-3 shows the timing of CPU read write in type 2 and the access cycle is 3-cycle access, figure 7-4 shows the timing of CPU read write in type 2 and the access cycle is 2-cycle access.

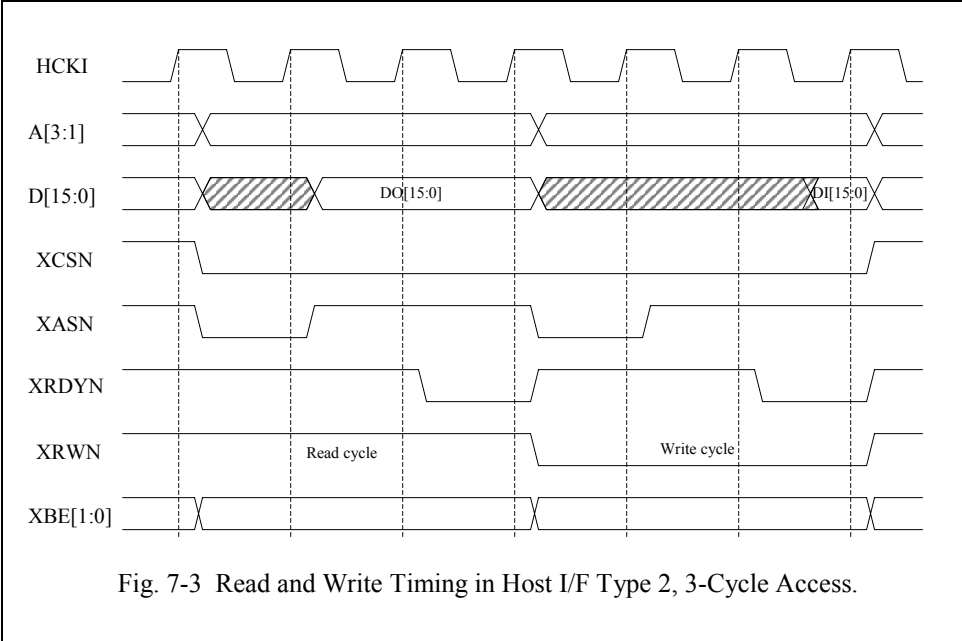


Fig. 7-3 Read and Write Timing in Host I/F Type 2, 3-Cycle Access.

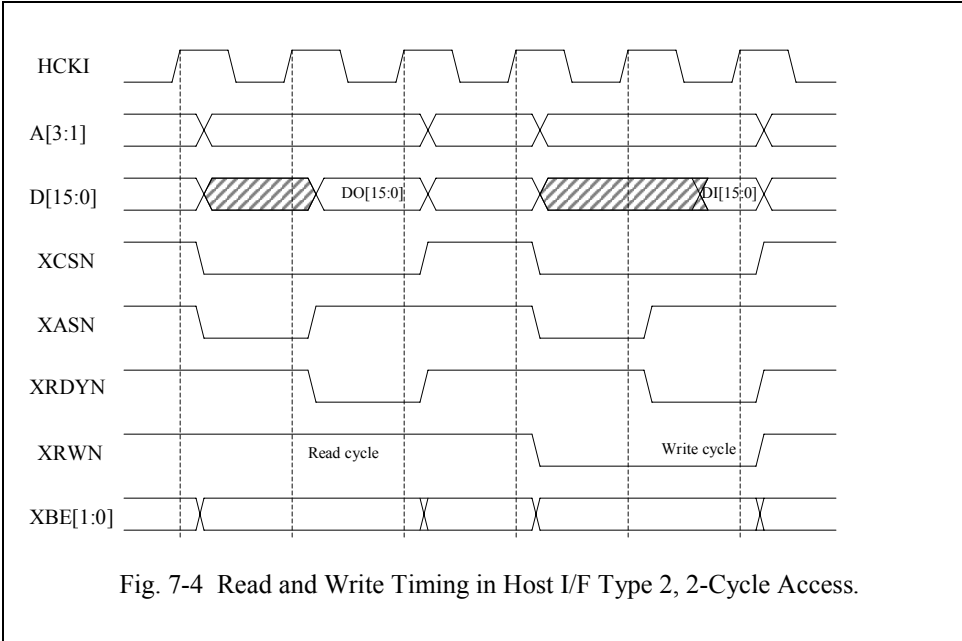


Fig. 7-4 Read and Write Timing in Host I/F Type 2, 2-Cycle Access.



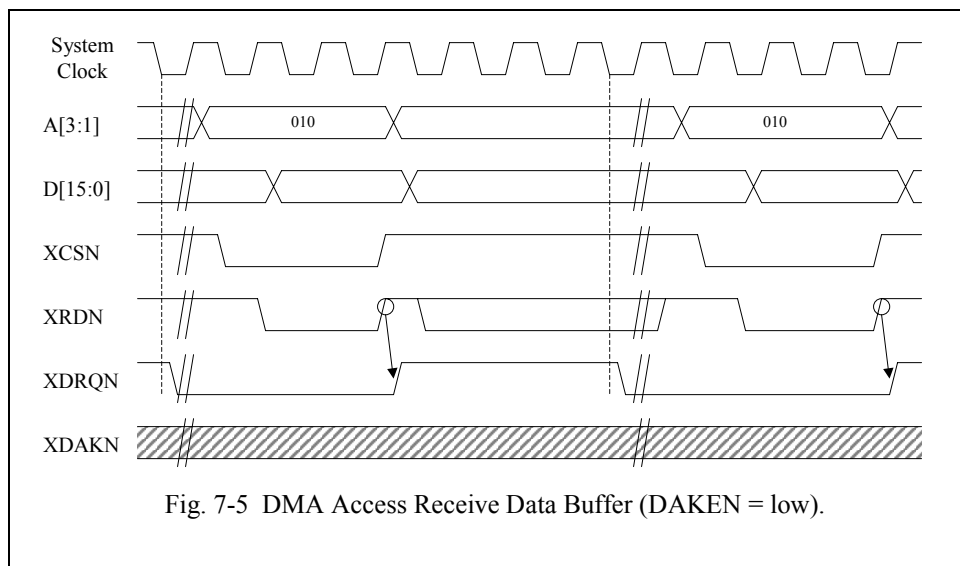
DMA Access:

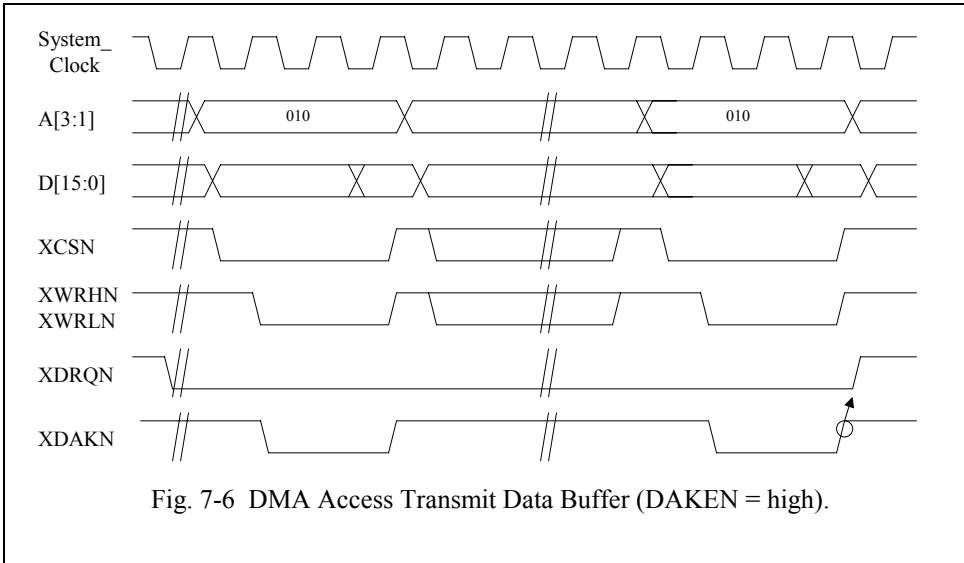
DMA request XDRQN is used to notify the Host that the Host should write data to the transmit data buffer or read data from the receive data buffer in data write to the card or data read from the card.

During data transmit to the card, the XDRQN will active if the data write command has been transfer to the card and the transmit data buffer have not enough data to transmit to the card. The XDRQN will not active if the transmit data buffer have enough data to transmit to the card.

During data receive from the card, the XDRQN will active if the data read command has been transfer to the card and the data have been received in the receive data buffer. The XDRQN will not active if the data read command has been executed completely and the receive data buffer is read out.

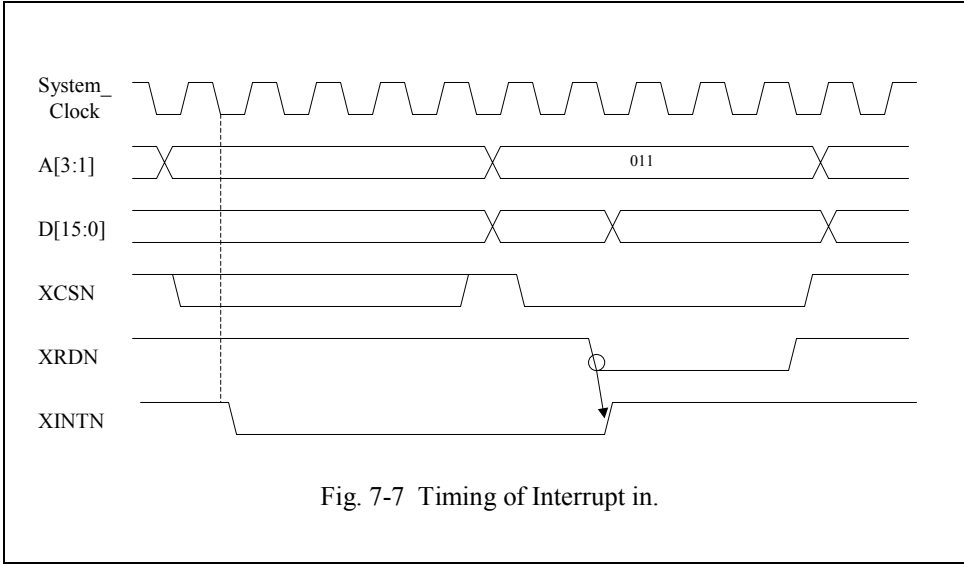
There are two types of DMA acknowledge waveform, the first type is configured if DAKEN = low, XDAKN is ignore and XDRQN will inactive after each access receive or transmit data buffer, the XDRQN will re-active after four clock later. Figure 7-5 shows the waveform of DMA access receive data buffer in DAKEN = low. The second type is configured if DAKEN = high, XDAKN is used to count the transfer count of the data buffer, XDRQN will hold at active state until the data has been transferred completely. Figure 7-6 is the waveform of DMA access transmit data buffer in DAKN = high.





6.1.1 Interrupt:

Interrupt pin XINTN will active (low) at the falling edge of system clock if any bit in the interrupt register is high, the XINTN pin will return to high when read the interrupt register and if the interrupt source is not existed. Figure 7-7 is the timing of interrupt.





6.2 Card Inserting and Removing

There are two methods for Host to detect SD/MMC card inserting or removing through W86L388, the first method is detected by CD/DAT3 pin, the second method is a dedicated switch on the SD/MMC slot can be connected to the GIO0 pin and set GIO0 to input direction. These two methods can be performed even if the W86L388 is in power down state.

Method 1, CD/DAT3 as card detection:

The CD/DAT3 of SD bus can be used as card detection if no data transfer on the DAT3, if SIEN bit on the control register is low and INS_IE and INT_E on the interrupt enable register are all high, card inserting or removing will generate interrupt. Host must read the interrupt status register and re-check the card state by reading the CD bit on the extend status register. This detection method will not be effective when wide bus on the SD bus is transfer. MMC card may not support this detection method.

Method 2, GIO0 as card detection:

Some SD/MMC slot support external switch for card existing detection, the switch will be on when SD or MMC is exist. GIO0 with a pull high resistor can be used as card detection, the Host can disable the GOEN0 bit on the general I/O port control register and enable the GIT_EN0 bit on the general I/O port interrupt enable register and enable GIT_IE and INT_E bits on the interrupt enable register. SD or MMC card inserting or removing will change the switch state then change the state of GIO0 pin and then general interrupt to the Host. Host may re-check the card state by reading the GIN0 bit on the general I/O port data register.

6.3 Reset Action

Hardware Reset:

Hardware reset is performed by setting RSTN pin to low state for at least 1 mS. The CPU data size will set to 16-bit default, all the registers will set to default value. The receive and transmit data buffer will be cleared; all the internal logic will be reset to initial state.

Software Reset:

Software reset is executed by writing the RST bit of the control register to 1, all the internal logic will be reset to initial state and receive and transmit data buffer will be cleared, but the content of registers are not affected.

Data Buffer Reset:

Data buffer reset is used to reset the receive data buffer and transmit data buffer simultaneously, the serial interface command will be affected if the data receive or transmit command is progressing. Internal logic state and the content of registers are not affected.

6.4 Clock Source

The clock source of W86L388 is the waveform of XTO pin, if crystal is connected, the frequency may be from 3.58MHz to 25MHz, if the clock source is from external clock, XTI may be used as clock input and the maximum frequency is 25MHz.



7. ELECTRICAL CHARACTERISTICS

7.1 Maximum Ratings*

	PARAMETER	SYMBOL	RATING	UNITS
1	Supply Voltage with respect to V_{VSS}	V_{VDD}	-0.3 to 6	V
2	Current at any pin other than supplies		0 to 10	mA
3	Storage Temperature	T_{st}	-65 to 150	°C

* Exceeding these values may cause permanent damage.

7.2 Recommended Operating Conditions

	CHARACTERISTICS	SYMBOL	RATING	UNIT
1	Operation Voltage (referenced to VSS pin).	V_{VDD}	3.0 to 3.6	V
2	Operation Voltage (referenced to VSS pin) (Note)	V_{VDD}	2.7 to 3.0	V
3	Clock Frequency at XTI pin	f_{XTL}	25	MHz
4	Operation Temperature	T_{op}	0 to 70	°C

Note: Clock frequency not guaranteed up to 25MHz.

7.3 Power Supply Characteristics

	PARAMETER	CONDITION	SYMBOL	MIN	TYP‡	MAX	UNITS	TEST
1	Standby Supply Current	Power Supply	I_Q		2	20	uA	Test 1
2	Operating Supply Current	($V_{VDD} = 3.3V$)	I_{VDD}		TBD	TBD	mA	Test 2
3	Operating Supply Current		I_{VDD}		TBD		mA	Test 3

‡: Typical figure are at $V_{DIVDD} = 3.3V$ and temperature = 25 °C and are for design aid only, not guaranteed and not subject to production testing.

Test 1: All input pins are V_{VDD} or V_{VSS} , configured as power down mode, output without loading and no clock input on the XTI and HCKI pins.

Test 2: 20 MHz external clock input on the XTI pin, output without loading.

Test 3: 20 MHz crystal connected at XTI and XTO pins, output without loading.



7.4 Digital Characteristics

	PARAMETER	CONDITION	SYMBOL	MIN	TYP‡	MAX	UNITS	NOTES
1	Output High Voltage	2mA load	V _{OH}	0.9			VDD	1
2	Output Low Voltage	2mA sink	V _{OL}			0.1	VDD	1
3	Output High Voltage at SD4 output	3mA load	V _{OH}	0.9			VDD	
4	Output Low Voltage at SD4 output	3mA sink	V _{OL}			0.1	VDD	
5	High Level Input Voltage		V _{IH}	0.7			VDD	
6	Low Level Input Voltage		V _{IL}			0.3	VDD	
7	Input Current		I _{in}			1	uA	
8	Input Capacitance		C _{in}		10		pF	

‡: Typical figure are at V_{DVDD} = 3.3V and temperature = 25 °C and are for design aid only, not guaranteed and not subject to production testing.

Notes:

1: All output pins except SD4 output.

7.5 Timing Characteristics

	PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Clock (figure 8-1)							
1	XTI	fXTI	1	-	20	MHz	1
2	XTI high pulse width	tXTI _{wh}	10	-	-	nS	1
3	XTI low pulse width	tXTI _{wl}	10	-	-	nS	1
4	XTI rise time	tXTI _r	-	-	5	nS	1
5	XTI fall time	tXTI _f	-	-	5	nS	1
5	XTO delay time	tXTO _d	-	-	5	nS	2
6	XTI crystal driver	fXTI	3.58	-	25	MHz	3
7	HCLK frequency	fHCLK	1	-	40	MHz	
8	HCLK high pulse width	tHCLK _{wh}	10	-	-	nS	
9	HCLK low pulse width	tHCLK _{wl}	10	-	-	nS	
10	HCLK rise time	tHCLK _r	-	-	5	nS	
11	HCLK fall time	tHCLK _f	-	-	5	nS	



8.5. Timing Characteristics, continued

	PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Reset							
1	RSTN	tRST	4	-	-	cycle	
Host Interface at Type 1 (figure 8-2, 8-3)							
1	Access time	t _{acc}	100	-	-	nS	4
2	Address setup time	tA _{su}	10	-	-	nS	
3	Address hold time	tA _h	5	-	-	nS	
4	D[15:0] output delay time	tD _{od}	-	-	30	nS	5,6
5	D[15:0] output hold time	tD _{oh}	10	-	-	nS	5,7
6	D[15:0] input setup time	tD _{su}	10	-	-	nS	8
7	D[15:0] input hold time	tD _h	5	-	-	nS	9
8	DMA request delay time	tDRQ _d	-	-	20	nS	2
9	DMA request hold time	tDRQ _h	5	-	20	nS	2
Host Interface at Type 2 (figure 8-5)							
1	Input signals setup time	tIF2 _{su}	10	-	-	nS	10
2	Input signals hold time	tIF2 _h	5	-	-	nS	10
3	Address setup time	tA2 _{su}	10	-	-	nS	
4	Address hold time	tA2 _h	5	-	-	nS	
5	XRDYN delay time	tRDY _d	-	-	20	nS	2
6	XRDYN hold time	tRDY _h	5	-	-	nS	2
7	D[15:0] output delay time	tD _{od}	-	-	30	nS	5
8	D[15:0] output hold time	tD _{oh}	10	-	-	nS	5
9	D[15:0] input setup time	tD _{su}	10	-	-	nS	
10	D[15:0] input hold time	tD _h	5	-	-	nS	
Interrupt (figure 8-4)							
1	Interrupt delay time	tINT _d	-	-	20	nS	
2	Interrupt hold time	TINT _h	5	-	20	nS	



8.5. Timing Characteristics, continued

	PARAMETER	SYMBOL	MIN	TYP	MAX	UNITS	NOTES
Serial Interface Signals (figure 8-6, 8-7, 8-8, 8-9)							
1	SD3 output delay	t_{SD3d}	5	-	15	nS	2
3	SD3 input setup time	$t_{SD3D_{su}}$	10	-	-	nS	
4	SD3 input hold time	t_{SD3h}	5	-	-	nS	
2	SD1,SD2,SD5,SD6 output delay time	$t_{SDn_d}^*$	-	-	30	nS	2
3	SD1,SD2,SD5,SD6 input setup time	$t_{SDn_{su}}$	10	-	-	nS	
4	SD1,SD2,SD5,SD6 input hold time	t_{SDn_h}	5	-	-	nS	

Note 1: External clock input.

Note 2: 20 pF output loading.

Note 3: Crystal driver.

Note 4: Minimum active pulse width of (XCSN and XRDN) or (XCSN and XWRHN and XWRLN).

Note 5: 40 pF output loading.

Note 6: From the last active signal of XCSN or XRDN.

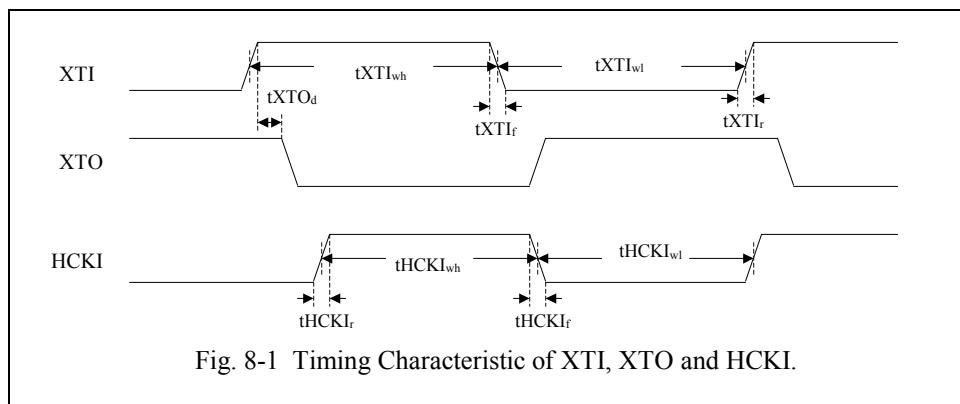
Note 7: From the first in-active signal of XCSN or XRDN.

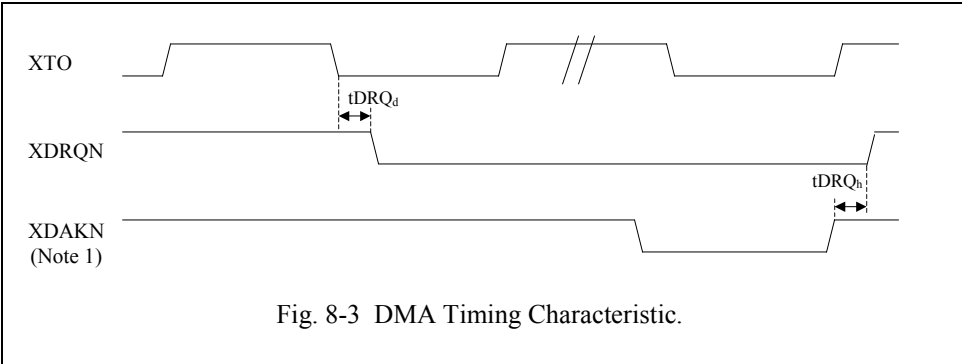
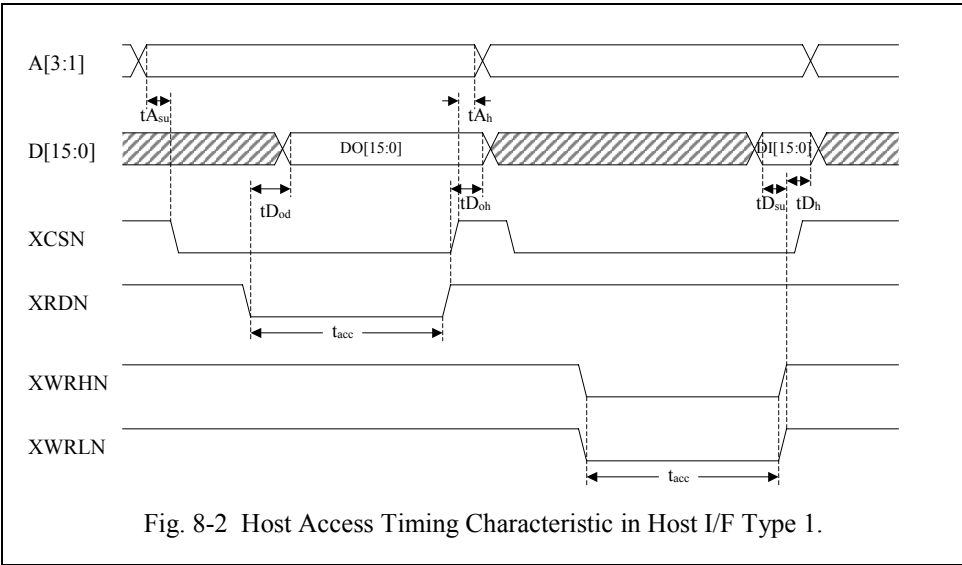
Note 8: To the first in-active signal of XCSN, XWRHN or XWRLN, XWRHN or XWRLN related to the D[15:8] or D[7:0].

Note 9: From the first in-active signal of XCSN, XWRHN or XWRLN, XWRHN or XWRLN related to the D[15:8] or D[7:0].

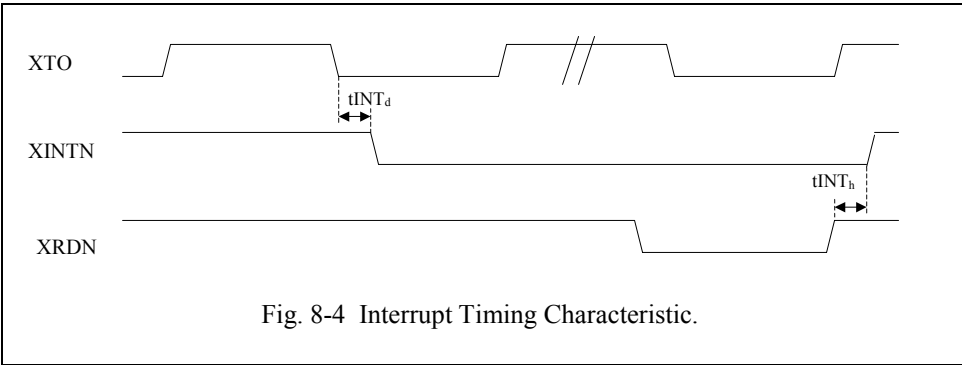
Note 10: XCSN, XASN, XRWN and XBE[1:0] signals.

Note 11: SDn: SD1, SD2, SD5, SD6





Note 1: May be XRDN or XWRHN or XWRLN signals when XDAKEN = low.



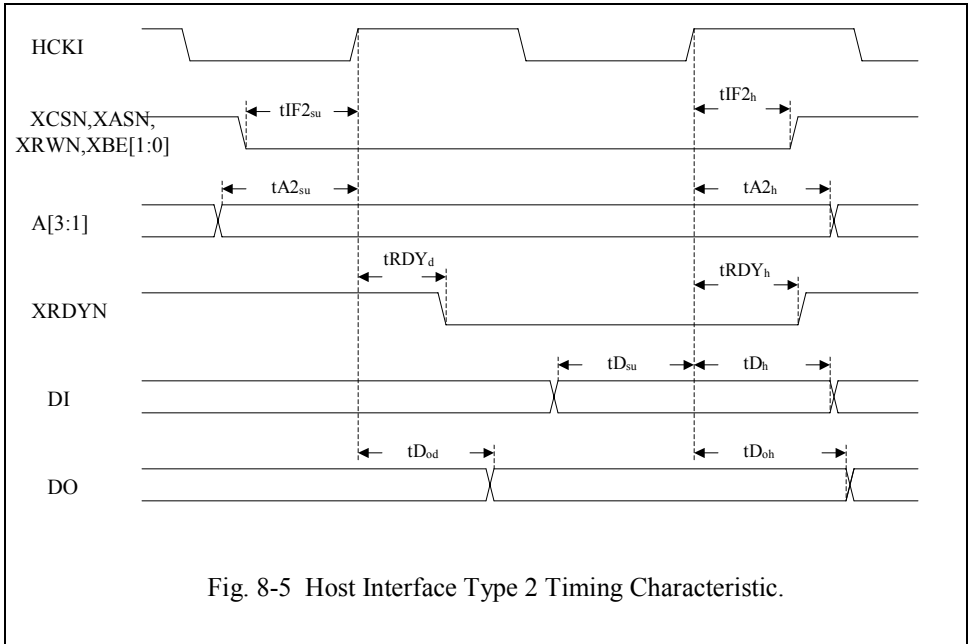


Fig. 8-5 Host Interface Type 2 Timing Characteristic.

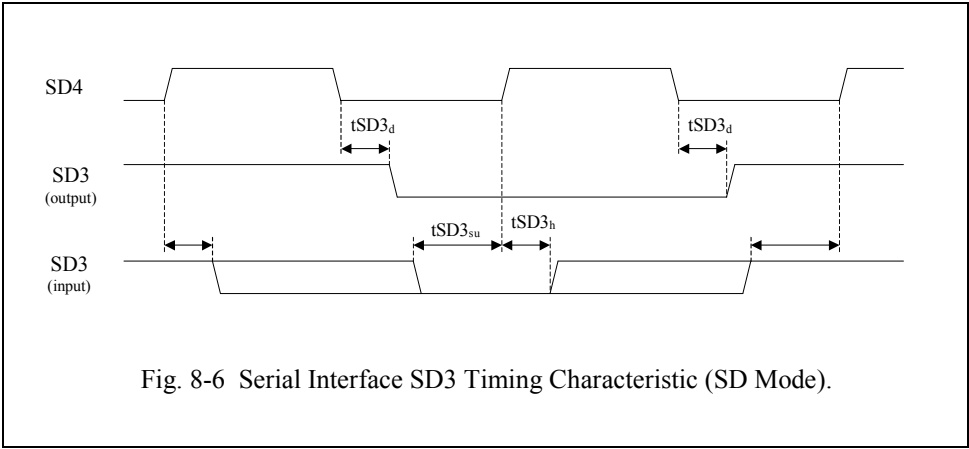


Fig. 8-6 Serial Interface SD3 Timing Characteristic (SD Mode).

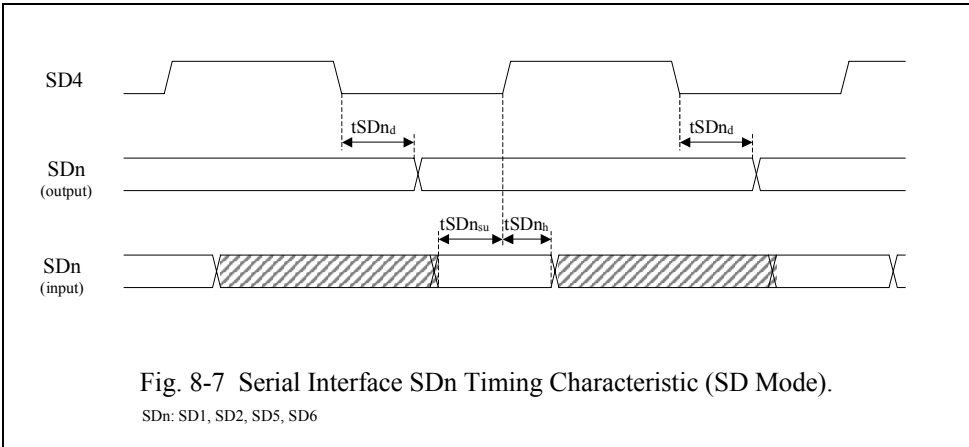


Fig. 8-7 Serial Interface SDn Timing Characteristic (SD Mode).
SDn: SD1, SD2, SD5, SD6

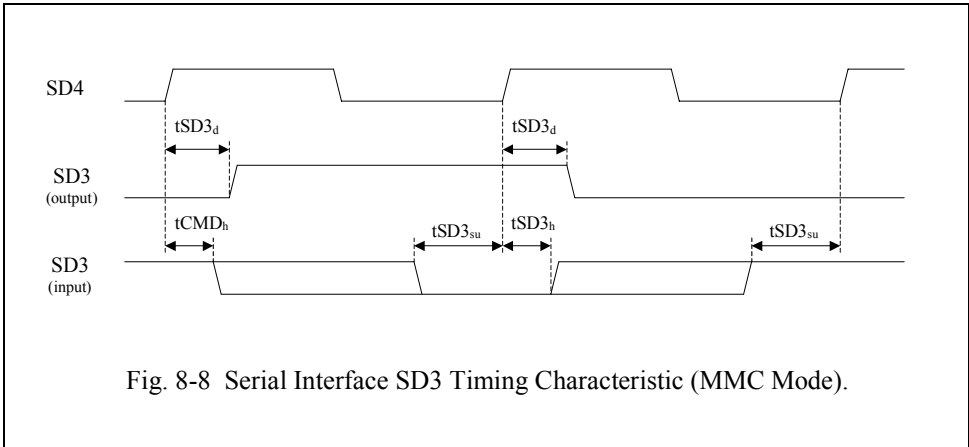


Fig. 8-8 Serial Interface SD3 Timing Characteristic (MMC Mode).

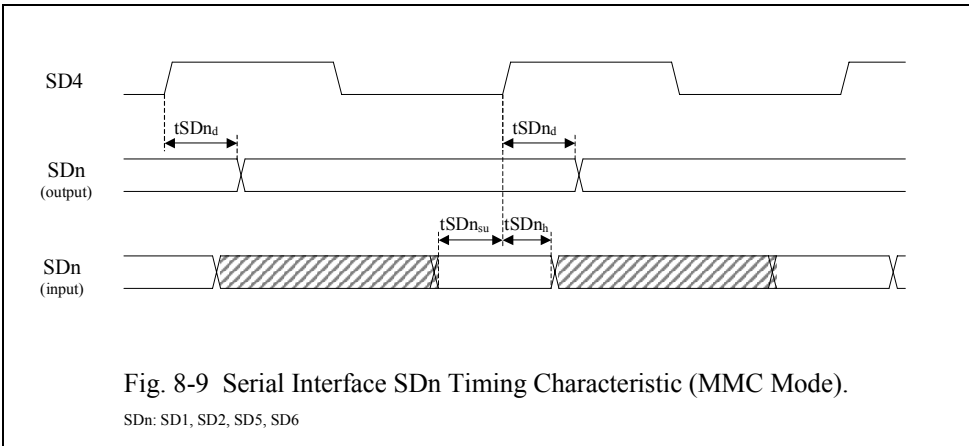


Fig. 8-9 Serial Interface SDn Timing Characteristic (MMC Mode).
SDn: SD1, SD2, SD5, SD6

W86L388D



8. HOW TO READ THE TOP MARKING

The top marking of W86L388D



1st line: Winbond logo and SMART@IO Mark

2nd line: Part number of W86L388D

3rd line: Tracking code 118 G A 01A SB

118: packages made in '01, week 18

G: assembly house ID; A means ASE, O means OSE, G means GR

A: IC revision; A means version A, B means version B

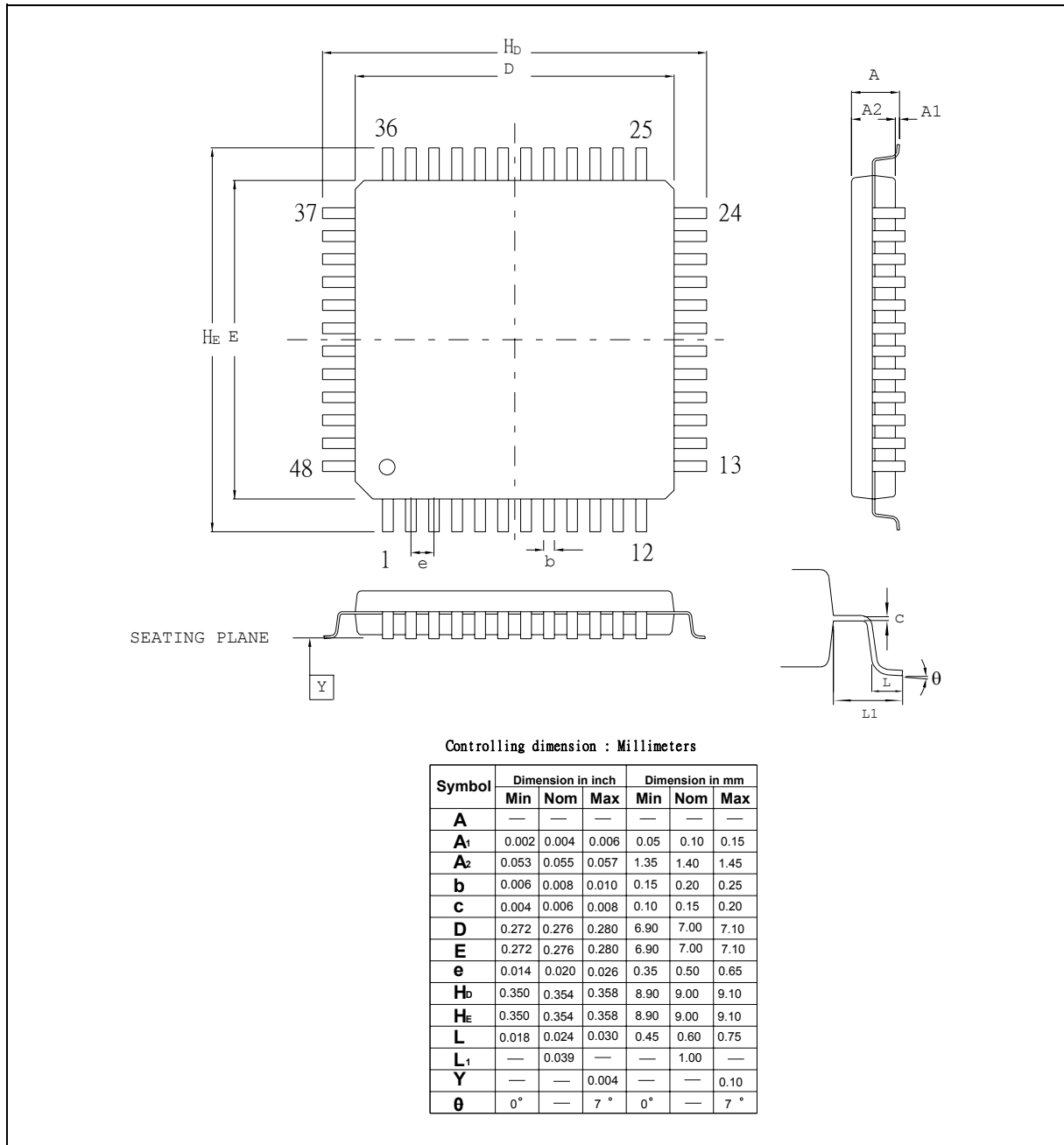
01A: for internal use

SB: for internal use



9. PACKAGE DIMENSIONS

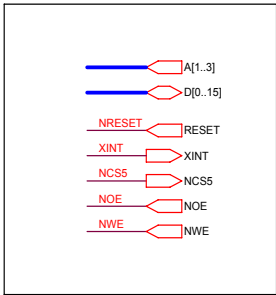
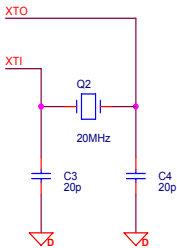
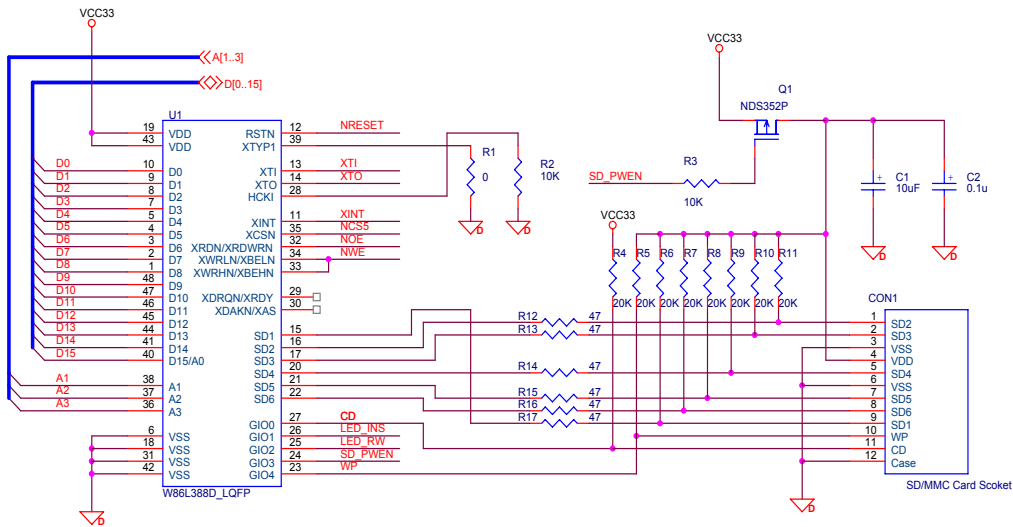
48-LQFP (7x7x1.4mm footprint 2.0mm)



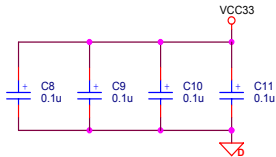
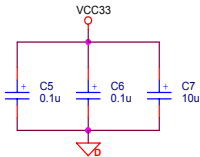
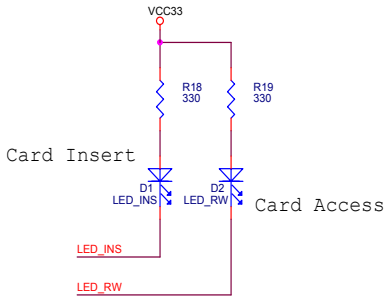


10. REFERENCE SCHEMATIC

W86L388D Reference Circuit



To Intel StrongARM interface (16 bit)



Winbond
WINBOND ELECTRONICS CORP.

Size	Document Number	Rev
	W86L388D Reference Schematic (for StrongARM)	2.2
Date:	Tuesday, October 02, 2001	Sheet 1 of 1



11. REVISION HISTORY

VERSION	DATE	PAGE	DESCRIPTION
1.0	May 17, 2005	23	Add Important Notice

Important Notice

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